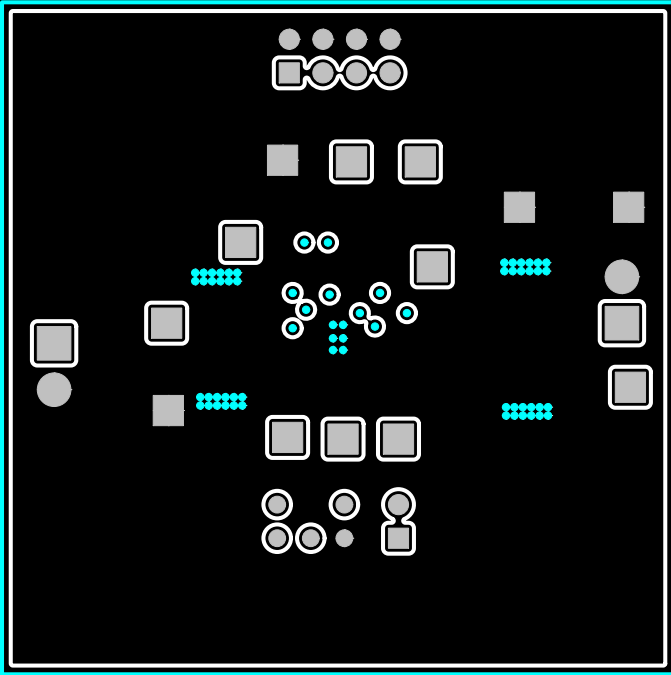
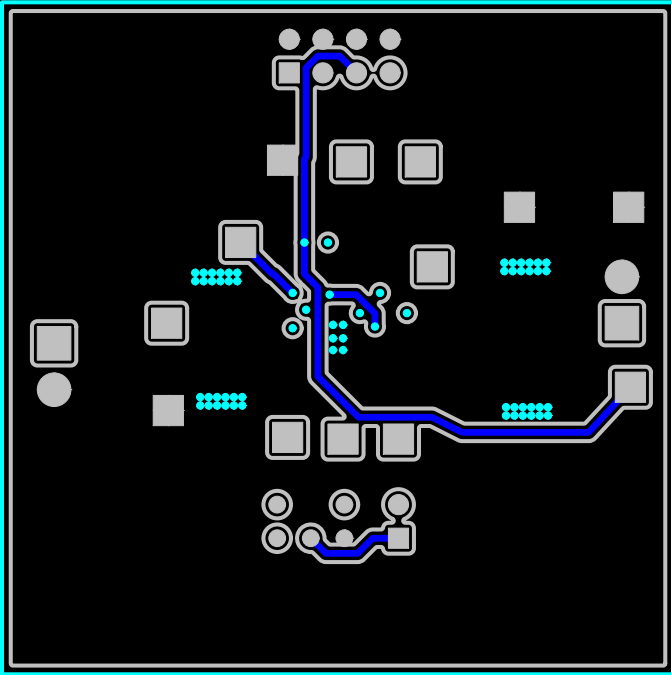


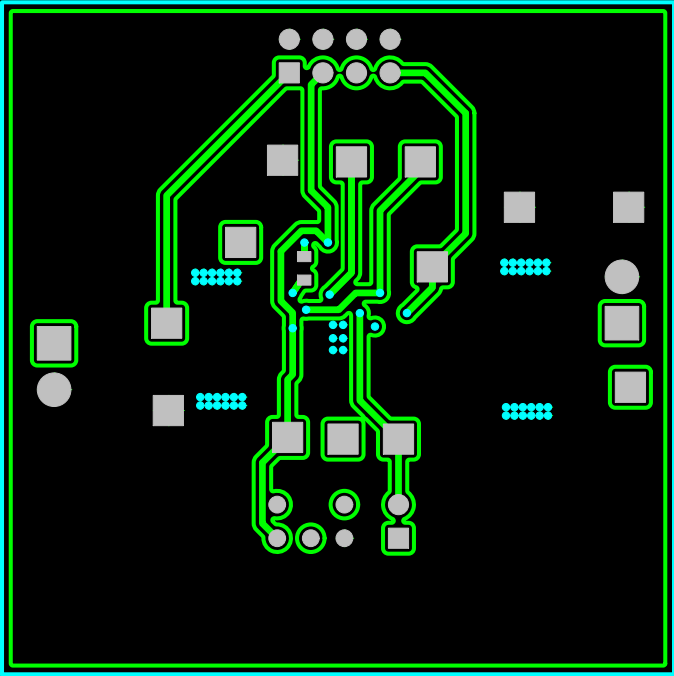
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM		Rev.	Rev. A		L1								
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}				Software	PADS v9.3



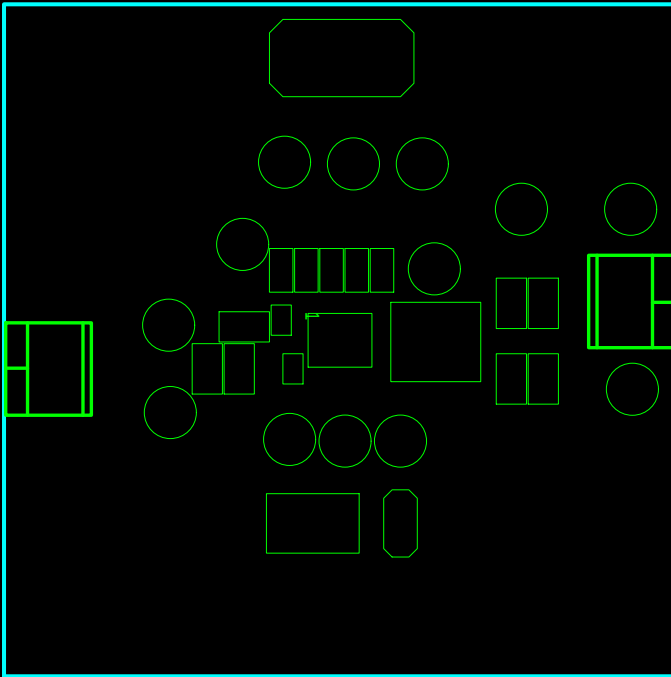
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM		Rev.	Rev. A			L2							
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}		Software	PADs v9.3		



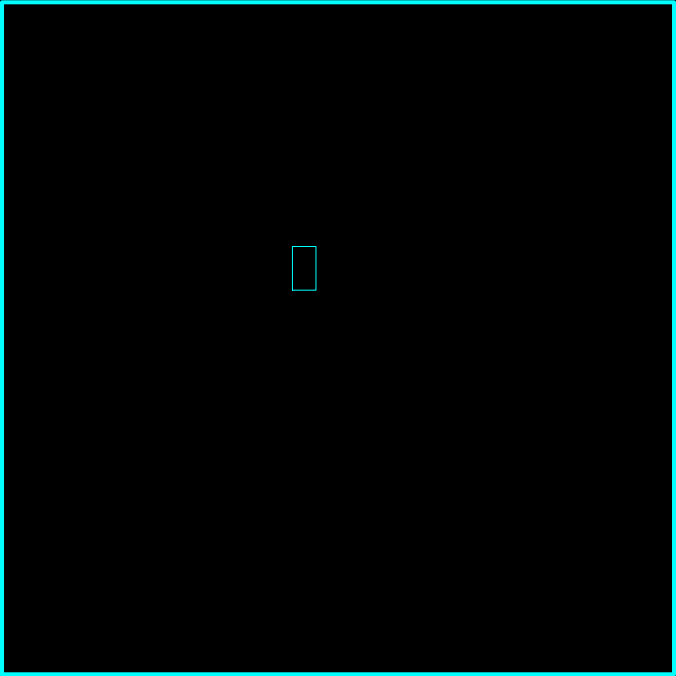
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM	Rev.	Rev. A		L3									
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}	Software	PADS v9.3			



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM	Rev.	Rev. A				L4							
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}	Software	PADS v9.3			



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM	Rev.	Rev. A	L1								TA		
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}	Software	PADS v9.3			

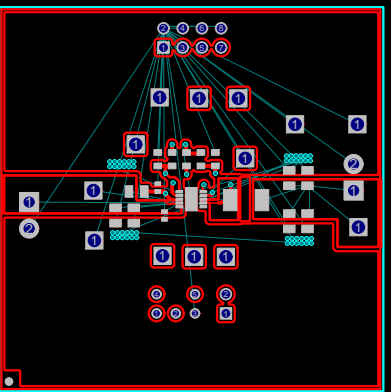


TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	TPS51312 EVM	Rev.	Rev. A			L4							BA	
Date:	June-25-2011	Filename:	TPS51312 EVM	Engineer:	Xiao Xu	PCB Dsgnr:	Anousone Sibounheuang	Modified Date:	{Modification Date}	Software	PADS v9.3			

THICKNESS	SILKSCREEN	SOLDERMASK	EXTEN
<input type="checkbox"/> 0.031	<input checked="" type="checkbox"/> LAYER 1	<input checked="" type="checkbox"/> LAYER 1	<input type="checkbox"/> 1 OZ.
<input checked="" type="checkbox"/> 0.062	<input type="checkbox"/> LAYER 2	<input checked="" type="checkbox"/> LAYER 2	<input checked="" type="checkbox"/> 2 OZ.
<input type="checkbox"/> 0.093	<input type="checkbox"/> NONE	<input type="checkbox"/> NONE	<input type="checkbox"/> OTHE
<input type="checkbox"/> 0.125			
DESIGN	TRACE/GAP SPACING	LA	
<input type="checkbox"/> SMD	<input checked="" type="checkbox"/> 0.010/0.010	<input type="checkbox"/> SINGLE SID	
<input type="checkbox"/> THRU-HOLE	<input type="checkbox"/> 0.008/0.007	<input checked="" type="checkbox"/> 4 LAYER	
<input checked="" type="checkbox"/> MIX	<input type="checkbox"/> 0.006/0.006	<input type="checkbox"/> 8 LAYER	
		<input type="checkbox"/> OTHER	

**NOTES: UNLESS OTHERWISE SPECIFIED**

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A GREEN EMISSION LEVEL.
- BASE LAMINATE:** PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SILKSCREEN LAYERS, EPOXY RESIN EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPRESSION MODULUS SHALL BE 1.0E+10 DYNES/CM<sup>2</sup>. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH IPC-2221. BOARD SHALL BE COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID APPLIED SOLDERMASK ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SCORING AND DISCOLORATION ON PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DISCOURTESY IS THE RESULT.
- TOLERANCES:** UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .0005 INCHES.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1.5 MILS THICK COPPER.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED. IMMERSION SILVER WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREA SHALL BE AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CORROSIVE INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCHED OR PRINTED). LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 PERFORMANCE.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTATION AND INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DRAWING NUMBER, MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED FROM TEXAS INSTRUMENTS.



<b>TEXAS INSTRUMENTS</b>		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. TPS51312 EVM	Rev. Rev. A	L1											FB
Date: June-25-2011	Filename: TPSS1312 EVM	Engineer: Xiao Xu	PCB Design: Anoussone Sibounheuang	Modified Date: (Modification Date)				Software: PADS v9.3					